

CDR03BX123BKUR

Aliases (C1808P123K1XRL, CDR03BX123BKZR, CDR03BX123BKWR)

SMD Mil PRF55681, Ceramic, 0.012 uF, 10%, 100 VDC, BP, Ceramic Chips, MIL PRF 55681 Established Reliability, R (0.01%/1000 Hrs), 1808



Click [here](#) for the 3D model.

| Dimensions | |
|------------|-----------------|
| Chip Size | 1808 |
| L | 2mm +/-0.2mm |
| W | 1.25mm +/-0.2mm |
| T | 1.3mm MAX |
| B | 0.5mm +/-0.2mm |

| Packaging Specifications | |
|--------------------------|-----------|
| Packaging | Bulk, Bag |
| Packaging Quantity | 1 |

| General Information | |
|-------------------------|--|
| Series | SMD Mil PRF55681 |
| Style | SMD Chip |
| Description | Ceramic Chips, MIL PRF 55681 Established Reliability |
| RoHS | No |
| Prop 65 | ⚠ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov . |
| Termination | Lead (SnPb) |
| Failure Rate | R (0.01%/1000 Hrs) |
| Testing and Reliability | MIL-PRF-55681 |
| Qualifications | MIL-PRF-55681 |
| AEC-Q200 | No |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Specifications | |
|---------------------------------|------------|
| Capacitance | 0.012 uF |
| Capacitance Tolerance | 10% |
| Voltage DC | 100 VDC |
| Dielectric Withstanding Voltage | 250 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | BP |
| Dissipation Factor | 0.15% |
| Insulation Resistance | 100 GOhms |

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